CLAIMS

1. A method of cutting an object to be processed, the method comprising:

a starting point region for cutting forming step of irradiating a wafer-like object to be processed with laser light while positioning a light-converging point therewithin, so as to form a modified region due to multiphoton absorption within the object, and causing the modified region to form a starting point region for cutting, deviated from a center position of the object in a thickness direction thereof toward one end face of the object, along a line along which the object should be cut in the object; and

a pressing step of pressing the object from the other end face side of the object.

2. A method of cutting an object to be processed according to claim 1, wherein the object is pressed along the line along which the object should be cut in the pressing step.

3. A method of cutting an object to be processed according to claim 2, wherein positional data of the line along which the object should be cut with respect to the object is stored in the starting point region for cutting forming step; and

wherein the object is pressed along the line along which the object should be cut according to the positional data in the pressing step.